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제품 정보

200µm x-linkable polyurethane black HAF mounting tape

제품 설명

200µm x-linkable polyurethane black HAF
mounting tape

Long description

tesa ® XPU 58708 is a reactive mounting
tape offering high bonding strength and elasticity after curing. This black
double-sided tape has no backing. It is protected by a PE-coated paper liner.

It is activated by heat and pressure applied during the assembly
process.

Special features:

Black design

특성

- Extremely high bonding performance and reliability, even on thin design gaps
- Excellent shock resistance
- Extremely low oozing ratio
- tesa ® XPU 58708 is free of halogen according to IEC 61249-2-21 and compliant with current RoHS directive.
- At room temperature tesa ® XPU 58708 is not tacky.

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Applications

tesa ® XPU 58708 is especially recommended for structural bonding of various substrates inside electronic devices:

• Bonding of plastics

• Bonding of metals

• Bonding of electronic components

Technical Information (average values)

The values in this section should be considered representative or typical only
and should not be used for specification purposes.

제품 구조

• 기재 소재	없음	• 총두께	200 µm
• 점착제 종류	crosslinkable polyurethane	• 컬러	검정
• 이형지 종류	PE 코팅된 직물		

속성 / 성능 값

• 점착력 (푸쉬 아웃)	4 N/mm²

추가정보

Technical recommendations:

tesa® XPU 58708 is not self-adhesive. It is
activated by heat and pressure over a certain interval. The following values
are recommendations for bond line parameters to start with.

• Pre-lamination

During pre-lamination, laminate the
adhesive tape onto the first component.

Setting:

Temperature¹ 55-65 °C

Pressure² 3 bar

Time 5 – 20 s

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추가정보

Short-time exposure to 65 °C bond line
temperature during pre-lamination does not affect the final bonding potential.

2. Bonding

Remove the liner from tape after the
pre-lamination step.Position the second component.

Apply temperature and pressure for the
bonding time to reach sufficient bonding strength.

2.1. PC/PC:Setting:

• Temperature¹ 80 – 140 °C

• Pressure² 5 bar

• Time 10 – 120 s

2.2. AL/PC:Setting:

• Temperature¹ 110 – 190 °C

• Pressure² 5 bar

• Time 20 – 120 s

Short cycle times can be achieved at high
bond line temperatures. For activation at low temperatures, increase the heat-press
time. To reach maximum bonding strength, surfaces should be clean and dry.
Allow at least 1-2 hours dwell-time after bonding before performance testing.
Final bonding strength will be reached after 24 hours. Bonding strength values
were obtained under standard laboratory conditions. PC/PC: bonding conditions:
temperature = 110 °C

(120 °C jig); pressure = 5 bar; time = 60
sec Storage: tesa® recommends storage in original packaging in cool and dry conditions.

• 'Pre-lamination' and 'Bonding'
temperature refer to the data that is measured in the bond line.

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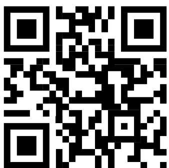

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